

# Global Dicing Blade Market, 2020-2026

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## Abstracts

Dicing blades are used with dicing and cutting saws to groove, cut, and dice silicon, compound semiconductors, glass, ceramics, crystals, and almost any other material. According to Gen Consulting Company, global dicing blade market is projected to grow at a CAGR of 5.7% during the forecast period 2020-2026.

The report offers a breakdown of market shares by product, including Hub Dicing Blades, Hubless Dicing Blades. By application, the dicing blade market is classified into Semiconductors, Glass, Ceramics, Crystals. On the basis of region, the dicing blade industry is analyzed across North America, Europe, Asia-Pacific, South America and MEA (the Middle East, and Africa).

By Product:

Hub Dicing Blades

Hubless Dicing Blades

By Application:

Semiconductors

Glass

Ceramics

Crystals

By region, the market is analyzed across North America, Asia Pacific, Europe, Middle East & Africa and South America. This report forecasts revenue growth at global, regional & country level from 2020 to 2026.

North America (U.S., Canada, Mexico, etc.)

Asia-Pacific (China, Japan, India, Korea, Australia, Indonesia, Taiwan, Thailand, etc.)

Europe (Germany, UK, France, Italy, Russia, Spain, etc.)

Middle East & Africa (Turkey, Saudi Arabia, Iran, Egypt, Nigeria, UAE, Israel, South Africa, etc.)

South America (Brazil, Argentina, Colombia, Chile, Venezuela, Peru, etc.)

The market research report covers the analysis of key stake holders of the dicing blade market. Some of the leading players profiled in the report include:

Advanced Dicing Technologies Ltd. (ADT)

Asahi Diamond Industrial Co., Ltd.

Compagnie de Saint-Gobain S.A.

DISCO Corporation

Ehwa Diamond Industrial Company Ltd.

Kulicke & Soffa Industries Inc.

Nanjing Sanchao Advanced Materials Co., Ltd.

Shanghai Sinyang Semiconductor Materials Co., Ltd.

Tokyo Seimitsu Co., Ltd.

\*list is not exhaustive, request free sample to get a complete list of companies

The base year of the study is 2019, and forecasts run up to 2026.

### Research Objective

To analyze and forecast the market size of global dicing blade market.

To classify and forecast global dicing blade market based on product, application.

To identify drivers and challenges for global dicing blade market.

To examine competitive developments such as mergers & acquisitions, agreements, collaborations and partnerships, etc., in global dicing blade market.

To conduct pricing analysis for global dicing blade market.

To identify and analyze the profile of leading players operating in global dicing blade market.

The report is useful in providing answers to several critical questions that are important for the industry stakeholders such as manufacturers and partners, end users, etc., besides allowing them in strategizing investments and capitalizing on market opportunities. Key target audience are:

Manufacturers of dicing blade

Raw material suppliers

Market research and consulting firms

Government bodies such as regulating authorities and policy makers

Organizations, forums and alliances related to dicing blade

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